

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Ekkehard MUEH, et al.

SERIAL NUMBER: 10/586,675

FILING DATE: July 20, 2006

FOR: SILICON COMPOUNDS FOR PRODUCING SIO₂-CONTAINING INSULATING
LAYERS ON CHIPS

RESPONSE TO NOTICE OF MISSING REQUIREMENTS UNDER 35 USC 371

COMMISSIONER FOR PATENTS
BOX PCT
ALEXANDRIA, VIRGINIA 22313

SIR:

Responsive to the notification dated June 9, 2008, and in accordance with the provisions of 35 USC 371, Applicants submit herewith a date-stamped copy of the filing receipt evidencing the filing of the Rule 63 Declaration on July 20, 2006. A copy of the Rule 63 Declaration is also attached. The undersigned attorney hereby states that the copies being submitted herewith are in fact true copies of the papers filed on July 20, 2006.

Applicants also note that since the International Application was published in English, a translation is not required and therefore the additional fees are not due.

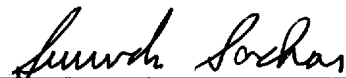
In light of the foregoing, this application is deemed to be in proper condition for examination and such favorable action is earnestly solicited.

Our payment in the amount of \$0.00 is paid herewith by credit card. If any difference exists between the amount due and the amount being paid herewith, please charge or credit the difference to our Deposit Account No. 15-0030.

If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136 and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030.

Respectfully Submitted,

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